

AMENDMENTS TO THE CLAIMS

1. (Currently amended) A method of preparing a plurality of electrically connected organic optoelectronic devices on a substrate comprising the steps of:

a) preparing a plurality of organic optoelectronic devices comprising[[;]]:

i) providing a substrate[[,]];

ii) providing a patterned layer of a first conductive material over said substrate[[,]];

iii) providing a layer of organic optoelectronic material over said layer of first conductive material; and,

iv) providing a patterned layer of a second conductive material over said layer of organic optoelectronic material, said patterned layer of second conductive material covering regions of said layer of organic optoelectronic material, said patterned layer of second conductive material defining a plurality of optoelectronic devices[[,]];

b) at least partially removing regions of said organic optoelectronic material that are not covered by said patterned layer of second conductive material[[,]]; and,

c) providing electrical connections to electrically connect at least two of said plurality of organic optoelectronic devices, wherein each electrical connection electrically connects the second conductive material of one optoelectronic device to the first conductive material of another optoelectronic device.

2. (Previously presented) A method according to claim 1 wherein said step of at least partially removing said organic optoelectronic material comprises removing said organic optoelectronic material using a method selected from the group consisting of dry etching, laser ablation, wet etching and scribing.

3. (Original) A method according to claim 1 wherein said step of at least partially removing said organic optoelectronic material comprises removing said organic optoelectronic material using dry etching.

4. (Original) A method according to claim 1 wherein said second conductive material partially overlies said first conductive material.

5. (Original) A method according to claim 1 wherein either said first conductive material and said substrate are at least semitransparent or said second conductive material is at least semitransparent.

6. (Original) A method according to claim 1 wherein said layer of organic optoelectronic material comprises at least an organic electron donor and at least an organic electron acceptor.

7. (Original) A method according to claim 6 wherein at least one of said organic electron donor and said organic electron acceptor comprises a semiconductive organic polymer.

8. (Original) A method according to claim 1 wherein said organic optoelectronic material comprises a light emitting polymer.

9. (Original) A method according to claim 1 further comprising the step of providing a layer of hole injecting or hole transporting material over said patterned layer of first conductive material.

10. (Original) A method according to claim 1 wherein said substrate comprises a plastic.

11. (Previously presented) A plurality of electrically connected organic optoelectronic devices on a substrate prepared according to the method of claim 1.

12. (Original) A plurality of electrically connected organic optoelectronic devices according to claim 11 wherein said organic optoelectronic devices comprise organic photovoltaic devices.

13. (Original) A plurality of electrically connected organic optoelectronic devices according to claim 11 wherein said organic optoelectronic devices comprise organic electroluminescent devices.

14. (Original) A plurality of electrically connected organic optoelectronic devices according to claim 11 wherein said organic optoelectronic devices comprise organic photovoltaic devices and organic electroluminescent devices.